



92/IFW

500.39825X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): T. HIROSE, et al
Serial No.: 09/800,495
Filed: March 8, 2001
For: METHOD OF DETECTING AND MEASURING ENDPOINT OF
POLISHING PROCESSING AND ITS APPARATUS AND
METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE
USING THE SAME
Group: 1765
Examiner: L. Umez-Eronini

STATEMENT OF SUBSTANCE OF INTERVIEW

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

October 20, 2004

Sir:

Applicants note that an Interview Summary accompanied the Notice of Allowance and confirm that the undersigned attorney conducted a telephone interview with the Examiner, L. Umez-Eronini, on September 20, 2004, during which time amendments to the claims 1 and 9 as effected by the Examiner's Amendment accompanying the Notice of Allowance and Interview Summary, were discussed and authorized in order to place the application in condition for allowance. Thus, applicants confirm the substance of the interview as provided by the Interview Summary and although applicants consider the submission of this paper to be unnecessary, to avoid any question concerning the requirements for applicant to file a statement of the substance of the interview, this statement is submitted.

Respectfully submitted,

Melvin Kraus
Registration No. 22,466
ANTONELLI, TERRY, STOUT & KRAUS, LLP

MK/cee
(703) 312-6600